



GLOBALFOUNDRIES is the world's first full-service semiconductor foundry with a truly global manufacturing and technology footprint. Launched in March 2009 through a partnership between AMD [NYSE: AMD] and the Advanced Technology Investment Company (ATIC), GLOBALFOUNDRIES provides a unique combination of advanced technology, manufacturing excellence and global operations. With the integration of Chartered in January 2010, GLOBALFOUNDRIES significantly expanded its capacity and ability to provide best-in-class foundry services from mainstream to the leading edge.

GLOBALFOUNDRIES is headquartered in Silicon Valley with manufacturing operations in Singapore, Dresden, and a new leading-edge fab under construction in Saratoga County, New York. These sites are supported by a global network of R&D, design enablement, and customer support in Singapore, China, Taiwan, Japan, the United States, Germany, and the United Kingdom.

For more information on GLOBALFOUNDRIES, visit www.globalfoundries.com

Job Summary:

This position is for a technical individual contributor within the Advanced Semiconductor Technology Alliance/International Semiconductor Development Alliance partnerships at IBM's facilities in East Fishkill, NY. The individual selected for this position will work together with GLOBALFOUNDRIES and Advanced Semiconductor Technology Alliance/International Semiconductor Development Alliance engineers in IBM's 300mm development facility. Employee will participate in joint development of advanced FEOL etch processes. Projects will include development and optimization of FEOL etch processes to enable modules for 20nm and 14nm technologies and beyond, linking with other process engineering and integration groups. In addition to development experience, experience optimizing etch processes for manufacturability will be important. The employee will also transfer technology developed in East Fishkill to GLOBALFOUNDRIES Fab8 in Malta, NY.

Specific Responsibilities Include:

- Collaborate with alliance partners and participate in joint development of advanced FEOL etch processes for 20nm & 14nm technologies and beyond.
- Drive development of advanced FEOL etch processes for 20nm & 14nm technologies and beyond.
- Design, execute, and analyze experiments to screen and optimize advanced FEOL etch processes and equipment to meet technology (e.g., performance, yield, and reliability) and manufacturing (e.g., process stability, cost of ownership) targets.
- Work with integration and device groups both in the alliance and the GLOBALFOUNDRIES manufacturing fabs to plan and execute projects and implement solutions on schedule.
- Engage with tool suppliers to highlight new FEOL etch process requirements and evaluate new equipment solutions.
- Define and maintain FEOL etch process and equipment roadmaps.
- Transfer technology developed in the alliance to the GLOBALFOUNDRIES productions fabs, in particular Fab8 in Malta, NY.

Required Qualifications:

- Must have a working knowledge of FEOL etch processes, and preferably, FEOL etch experience.
- Technology related Bachelor's degree plus 7 years, or a Master's degree plus 5 years or doctorate degree plus 2 years of experience in plasma etch process technology development. Exceptional new PhD candidates may be considered.
- Mastery of principles and working knowledge of various etch and/or deposition plasma processes and equipment.
- Demonstrated expertise in development of advanced etch processes and process technologies.
- Understanding of and familiarity with various characterization techniques including SEM, TEM, and voltage contrast.
- In-depth understanding and working knowledge of Statistical Process Control (SPC) and/or Design of Experiments (DOE).
- Ability to work effectively and efficiently with diverse teams, customers, internal and external partners.
- Outstanding written and verbal communication skills.
- Excellent interpersonal skills, energetic, and self starter
- Demonstrated ability to work well within a global matrixed team or environment
- Demonstrated ability to communicate well with all levels of the organization and experience in working with external constituencies
- Strong organizational skills; demonstrated ability to manage multiple tasks simultaneously and able to react to shifting priorities to meet business needs
- Demonstrated ability to meet deadlines and commitments

Preferred Qualifications:

- PhD in Physics, Chemistry, or Engineering
- FEOL etch experience at advanced technology nodes (32nm or below)
- Experience and understanding of high volume manufacturing preferred
- Understanding of FEOL integration is a plus.
- Alliance experience is a plus.

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